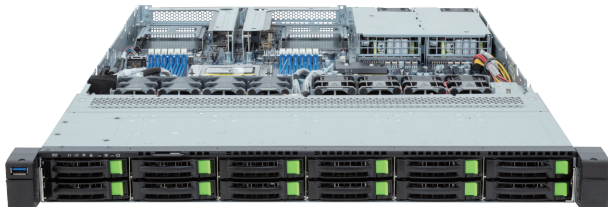# GIGABYTE™

R163-Z35-AAC1

Rack Server - 1U UP 12-Bay NVMe/SATA

AMD EPYC

- Single AMD EPYC™ 9005/9004 Series Processors
- 12-Channel DDR5 RDIMM, 12 x DIMMs
- Dual ROM Architecture
- 1 x 1Gb/s LAN port via Intel® I210-AT
- 12 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 1 x M.2 slot with PCIe Gen3 x4 interface
- 2 x FHHL PCIe Gen5 x16 slots
- 2 x OCP NIC 3.0 PCIe Gen5 x16 slots
- 2 x 1300W 80 PLUS Platinum redundant power supply

Application

Networking, Hybrid/Private Cloud Server...

Specification

Dimensions	1U (W438 x H43.5 x D710 mm)
Motherboard	MZ33-DC1
CPU	AMD EPYC™ 9005 Series Processors AMD EPYC™ 9004 Series Processors Single processor, cTDP up to 300W - At 25°C ambient, cTDP up to 400W
Sock	1 x LGA 6096 (Socket SP5)
Chipset	System on Chip
Memory	12-Channel DDR5 RDIMM 12 x DIMM slots [EPYC 9005] Up to 6000 MT/s [EPYC 9004] Up to 4800 MT/s
LAN	1 x 1Gb/s LAN (1 x Intel® I210-AT) - Supports NCSI function 1 x 10/100/1000 Mbps Management LAN
Video	Integrated in ASPEED® AST2600 - 1 x Mini-DP
Storage	Front hot-swap: 12 x 2.5" Gen5 NVMe/SATA/SAS-4 *SAS card is required to support SAS drives. Internal M.2: 1 x M.2 (2280/22110), PCIe Gen3 x4
RAID	Require RAID add-in cards
Expansion Slots	2 x FHHL PCIe Gen5 x16 slots 2 x OCP NIC 3.0 PCIe Gen5 x16 slots - Supports NCSI function

I/O Ports	Front: 1 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 1 x RJ45, 1 x MLAN
Backplane Board	Speed and bandwidth: PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
Security Modules	1 x TPM header with SPI interface - Optional TPM2.0 kit: CTM012
Power Supply	2 x 1300W 80 PLUS Platinum redundant power supply AC Input: 100-240V
System Management	ASPEED® AST2600 Baseboard Management Controller GIGABYTE Management Console web interface
OS Support	Windows Server, Red Hat Enterprise Linux server, Ubuntu, SUSE Linux Enterprise server, VMware ESXi, Citrix Hypervisor
System Fans	4 x 40x40x28mm (25,000rpm) 4 x 40x40x56mm (29,700rpm)
Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8%-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
Packaging Content	1 x R163-Z35-AAC1, 1 x CPU heatsink, 1 x Mini-DP to D-Sub cable, 1 x 2-Section Rail kit, Packaging Dimensions: 1038 x 588 x 238 mm
Part Numbers	Barebone package: 6NR163Z35DR000ACC1* Optional parts: - 3-Section Rail kit (Supports CMA): 25HB2-A56120-K0R - Cable Management Arm: 25HBZ-R18100-K0R

Learn more at **https://www.GIGABYTE.com/enterprise**

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